

**USB-MIC2.0B S1V 1N1 RL BK****Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

**General ordering data**

Version	OMNIMATE Data - USB jack, USB jacks, 480 Mbps, SMD solder connection, 180°, ≥ 10000, Pitch in mm (P): 0.65 mm, Number of poles: 5, LCP, black, Tape
Order No.	<a href="#">2762070000</a>
Type	USB-MIC2.0B S1V 1N1 RL BK
GTIN (EAN)	4064675035299
Qty.	2,000 pc(s).
Packaging	Tape

Creation date May 22, 2024 6:03:35 PM CEST

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## Technical data

## Dimensions and weights

Depth	2.9 mm	Depth (inches)	0.114 inch
Height	10.51 mm	Height (inches)	0.414 inch
Width	7.99 mm	Width (inches)	0.315 inch
Net weight	0.299 g		

## System specifications

LED	No	Mounting onto the PCB	SMD solder connection
Number of poles	5	Outgoing elbow	180°
Performance-Category	480 Mbps	Pitch in inches (P)	0.026 "
Pitch in mm (P)	0.65 mm	Plugging cycles	≥ 10000
Plugging force/pole, max.	35 N	Product family	OMNIMATE Data - USB jack
Protection degree	IP20	Pulling force / pole, min.	10 N
Shield surface	nickel-plated	Shielding	Yes
Shielding material	Stainless steel	Solder pin dimensions	Octagonal
Solder pin length (l)	0 mm	Soldering process	Reflow soldering, Manual soldering
Tolerance of solder pin position	± 0.1 mm	Transmission rate	480 Mbps
Type of connection	Socket connector		

## Electrical properties

Dielectric strength, contact / contact	100 V AC	Insulation strength	≥ 100 MΩ
Rated current	1 A	Rated voltage	48 V
Volume resistance	<25 mΩ		

## Material data

Insulating material	LCP	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 100 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact base material	Copper alloy	Contact material	Cu-alloy
Contact surface	Gold over nickel	Layer structure of plug contact	≤ 1 μ" Au
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-30 °C	Operating temperature, max.	80 °C

## Packing

Packaging	Tape	VPE length	462 mm
VPE width	450 mm	VPE height	166 mm

## Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01

## Approvals

ROHS	Conform
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## Technical data

### Downloads

Engineering Data

[CAD data – STEP](#)

Product Change Notification

[Änderung der Verpackung – 2762070000 USB-MIC2.0B S1V 1N1 RL BK](#)

[Change of packaging – 2762070000 USB-MIC2.0B S1V 1N1 RL BK](#)

Catalogues

[Catalogues in PDF-format](#)

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## Drawings

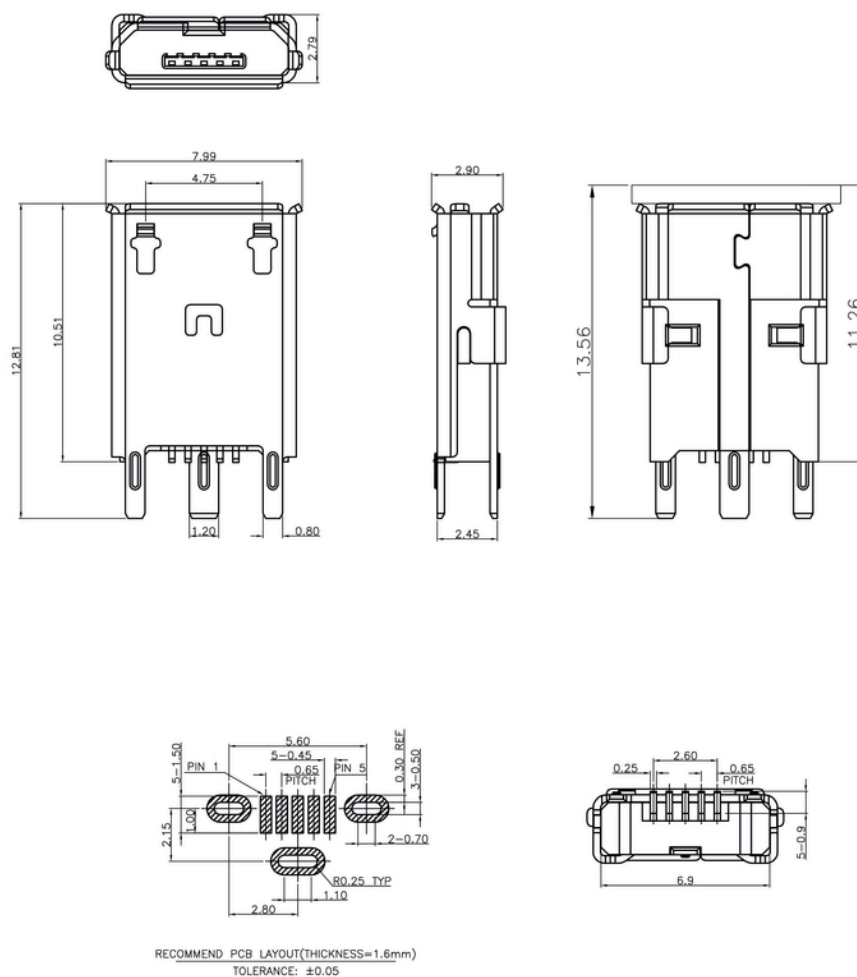


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[www.weidmueller.com](http://www.weidmueller.com)**Drawings**

## Recommended reflow soldering profile

**Weidmüller Interface GmbH & Co. KG**

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## Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3\text{K/s}$ . In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at  $\geq -6\text{K/s}$  solder is cured. Board and components cool down while avoiding cold cracks.